

IN THE SPECIFICATION

Please amend the paragraph bridging pages 15 and 16 to read as follows:

Fig. 1 is a section view showing a resin molded type semiconductor device of an embodiment of the invention, Fig. 1A illustrates the resin contacting the bottom of the chip, Fig. 2 is a plan view showing the resin molded type semiconductor device of the embodiment of the invention, Fig. 3 is an enlarged section view of main portions of the resin molded type semiconductor device of the embodiment of the invention, Fig. 4(a) is a plan view of an inner lead portion of the resin molded type semiconductor device of the embodiment of the invention, Fig. 4(b) is a left side view, Fig. 4(c) is a front view, Fig. 5 is a section view of a resin molded type semiconductor device of the prior art, and Fig. 6 is a section view showing another example of a resin molded type semiconductor device of the prior art.

Page 17, between lines 21 and 22, please insert the following new paragraph:

Fig. 1A shows chip 12 wider than die pad portion 11, with the resin 15 thus contacting the bottom of the chip. As noted below, there is contact through adhesiveness between the resin and the rear face of chip 12.